



## Material Content Data Sheet



<b>Sales Product Name</b>		TLS115B0EJ		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA003013986						
<b>Package</b>		PG-DSO-8-52		<b>Weight*</b>		83.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.123	1.34	1.34	13412	13412
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8693	
wire	non noble metal	copper	7440-50-8	29.548	35.30	36.22	352953	362190
	non noble metal	copper	7440-50-8	0.054	0.06	0.06	640	640
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1203
encapsulation	plastics	epoxy resin	-	4.635	5.54		55360	
	inorganic material	silicondioxide	60676-86-0	45.640	54.51	60.17	545177	601740
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8303	8303
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8654	8654
glue	plastics	epoxy resin	-	0.106	0.13		1265	
	noble metal	silver	7440-22-4	0.318	0.38	0.51	3796	5061
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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